

ABSTRACT OF THE DISCLOSURE

A method for manufacturing a semiconductor device having projection electrodes on the surface of a semiconductor substrate. This method include an electrode forming step of forming the projection electrodes on the surface of the semiconductor substrate, a step of forming a protective resin layer on the whole surface of the semiconductor substrate provided with the projection electrodes, a back side grinding step of thinning the semiconductor substrate by polishing or grinding the back side of the semiconductor substrate, and a surface grinding step of exposing the projection electrodes by polishing or grinding the surface side of the semiconductor substrate.

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